



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC060N10NS3 G		<b>Issued</b>		29. August 2013	
<b>MA#</b>				MA001065228					
<b>Package</b>				PG-TDSON-8-1		<b>Weight*</b>		122.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.423	3.62	3.62	36194	36194	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		309		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93		
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	309000	309402	
wire	non noble metal	copper	7440-50-8	0.065	0.05	0.05	533	533	
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		652		
	plastics	epoxy resin	-	5.660	4.63		46317		
	inorganic material	silicondioxide	60676-86-0	34.121	27.92	32.62	279210	326179	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11879	11879	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1354	1354	
solder	non noble metal	tin	7440-31-5	0.070	0.06		570		
	noble metal	silver	7440-22-4	0.087	0.07		713		
	non noble metal	lead	7439-92-1	3.327	2.72	2.85	27224	28507	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	iron	7439-89-6	0.011	0.01		93		
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92631	92752	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	noble metal	silver	7440-22-4	1.289	1.06		10552		
	non noble metal	copper	7440-50-8	22.292	18.24	19.33	182410	193200	
*deviation	< 10%					Sum in total:	100,00	1000000	

### Important Remarks:

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